

FM240-L-Q1 THRU FM2200-L-Q1

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FM240-L-Q1 THRU FM2200-L-Q1

2.0A Surface Mount Schottky Barrier Rectifiers 40V-200V

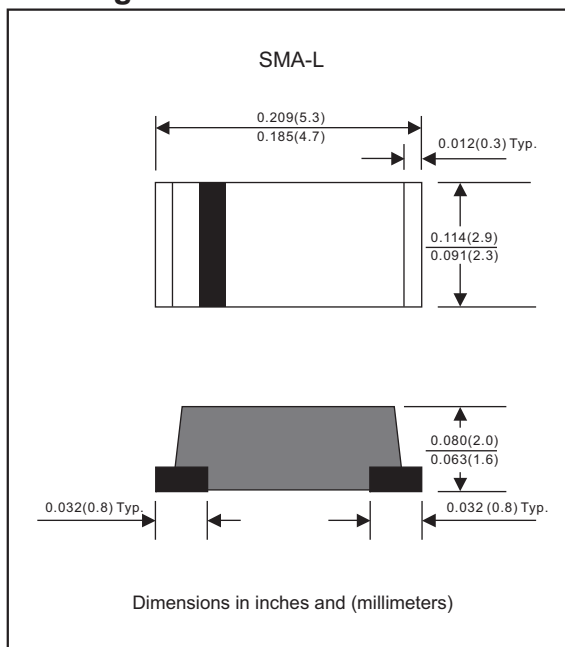
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- Guardring for overvoltage protection
- Ultra high-speed switching
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates Halogen free parts, ex. FM240-L-Q1-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMA-L
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.05 gram

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	FM240-L-Q1	FM260-L-Q1	FM2100-L-Q1	FM2150-L-Q1	FM2200-L-Q1	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	60	100	150	200	Volts
Maximum RMS voltage	V_{RMS}	28	42	70	105	140	Volts
Maximum continuous reverse voltage	V_R	40	60	100	150	200	Volts
Maximum average forward rectified current	I_O	2.0					Amps
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I_{FSM}	50					Amps
Typical junction capacitance (Note 1)	C_J	110	80	60	45	35	pF
Operating junction temperature range	T_J	-55 to +125					$^\circ\text{C}$
Storage temperature range	T_{STG}	-65 to +175					$^\circ\text{C}$

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	FM240-L-Q1	FM260-L-Q1	FM2100-L-Q1	FM2150-L-Q1	FM2200-L-Q1	UNITS
Maximum instantaneous forward voltage at $I_F=2.0A$	V_F	0.50	0.70	0.85	0.90	0.92	Volts
Maximum reverse leakage current at rated V_R $T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$	I_R	0.5 10					mA mA

Thermal characteristics

PARAMETER	SYMBOLS	FM240-L-Q1	FM260-L-Q1	FM2100-L-Q1	FM2150-L-Q1	FM2200-L-Q1	UNITS
Typical thermal resistance junction to ambient (Note 2)	$R_{\theta JA}$	62					$^\circ\text{C} / \text{W}$
Typical thermal resistance junction to case (Note 2)	$R_{\theta JC}$	31					$^\circ\text{C} / \text{W}$

Notes1: Measured at 1MHz and applied reverse voltage of 4.0V D.C

2: Mounted on FR-4 PCB copper, minimum recommended pad layout

Rating and characteristic curves (FM240-L-Q1 THRU FM2200-L-Q1)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

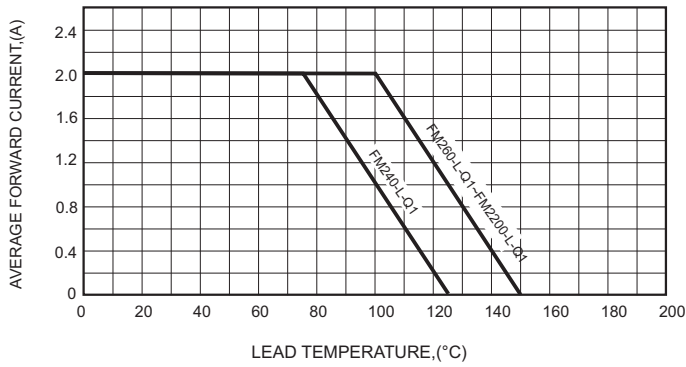


FIG.2-TYPICAL FORWARD CHARACTERISTICS

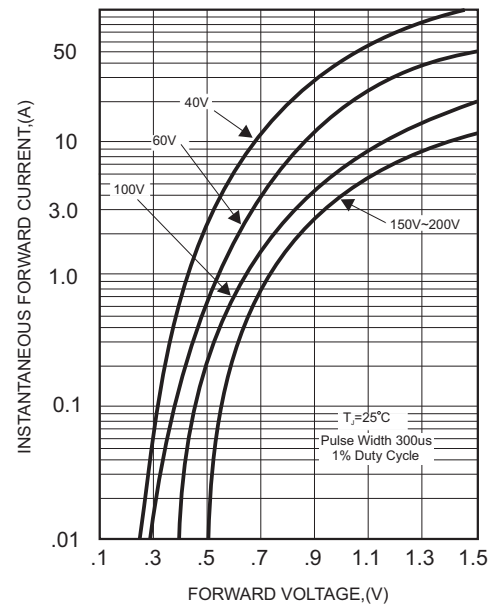


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

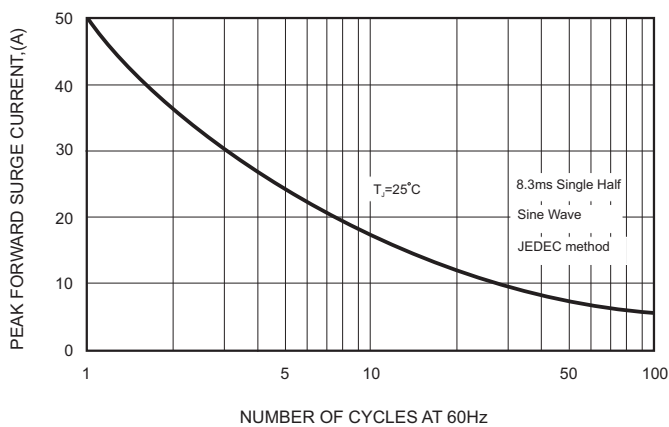


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

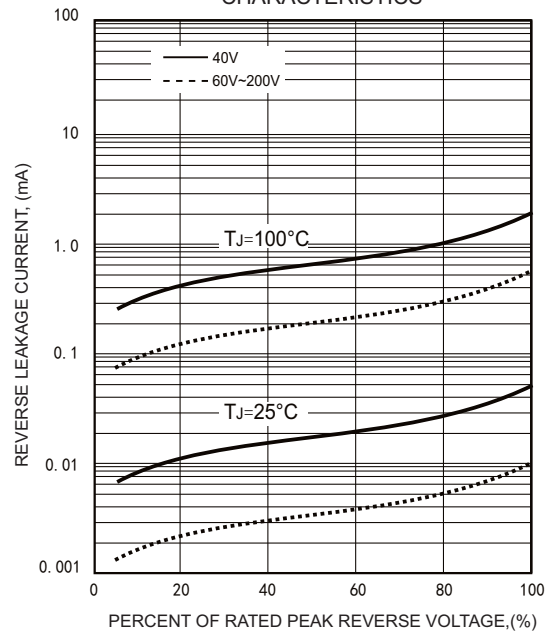
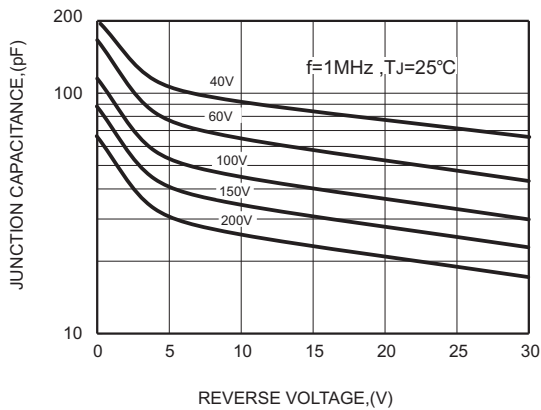


FIG.4-TYPICAL JUNCTION CAPACITANCE



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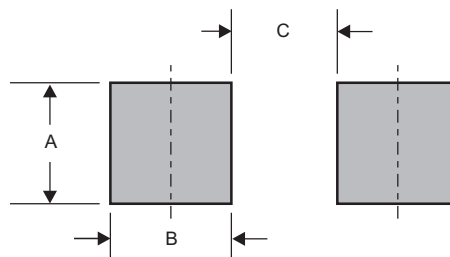
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
FM240-L-Q1	SK24
FM260-L-Q1	SK26
FM2100-L-Q1	S210
FM2150-L-Q1	S215
FM2200-L-Q1	S220

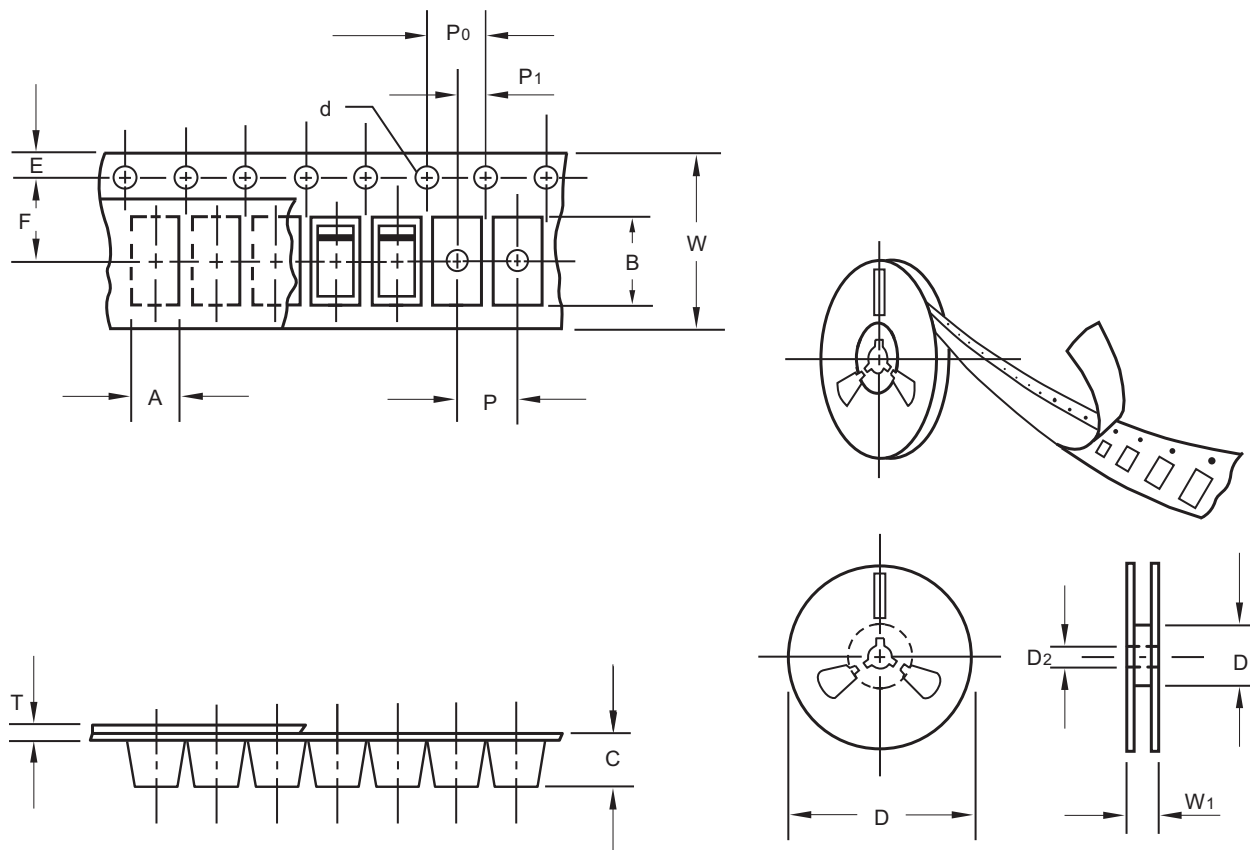
Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA-L	0.110 (2.80)	0.059 (1.50)	0.110 (2.80)

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unit:mm

Item	Symbol	Tolerance	SMA-L
Carrier width	A	0.1	2.90
Carrier length	B	0.1	5.50
Carrier depth	C	0.1	2.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

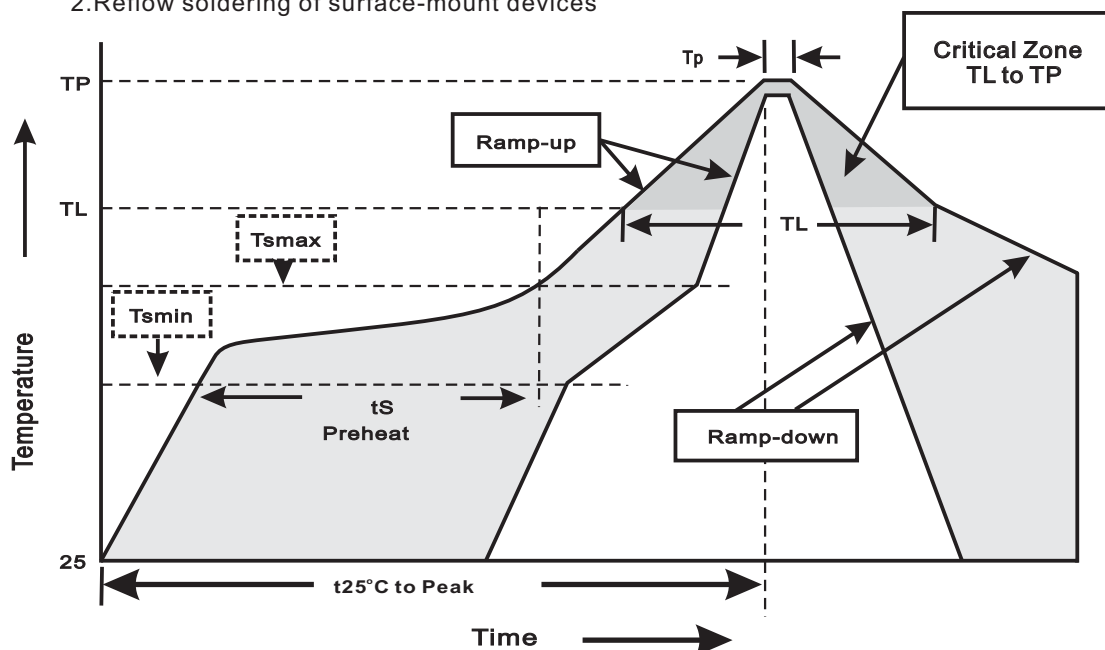
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA-L	7"	2,000	4.0	20,000	183*155*183	178	382*356*392	160,000	15.5
	7"	2,000	4.0	10,000	180*180*80	178	440*410*220	100,000	13.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$

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High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C, Rated Current (Io=Io max.) Test Duration: 1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tj max.) Test Duration: 1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration: 1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min) Test Cycles: 1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration: 96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C, On/lo Max. 2min, Off/2min, Test Cycles: 15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration: 1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration: 1000hrs	JESD22-A101